Lattice Semiconductor Corporation - LFXP10C-3F256C Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	10000
Total RAM Bits	221184
Number of I/O	188
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp10c-3f256c

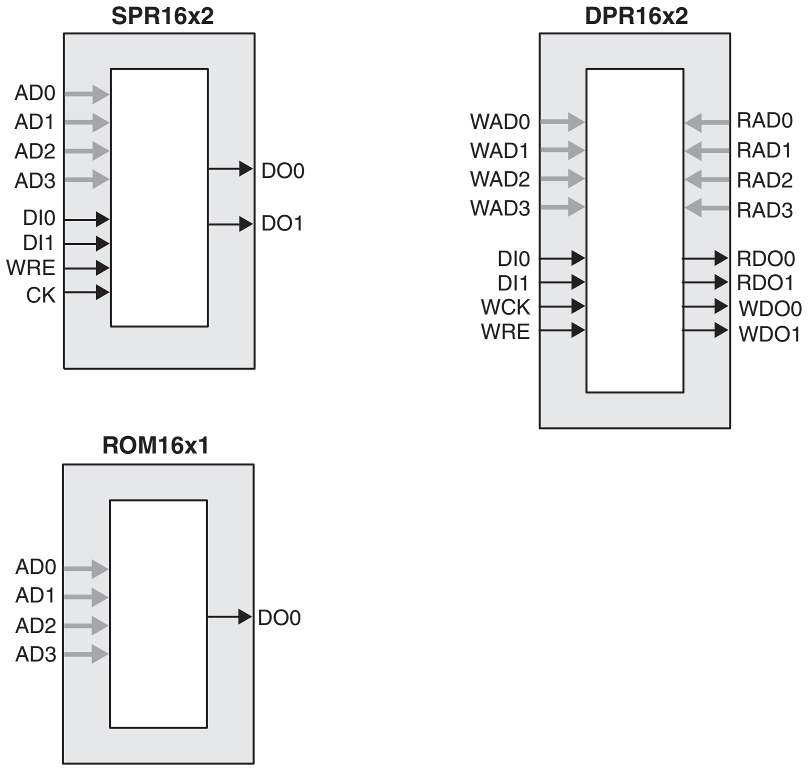
The Lattice design tools support the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the PFU. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Figure 2-4 shows the distributed memory primitive block diagrams. Dual port memories involve the pairing of two Slices, one Slice functions as the read-write port. The other companion Slice supports the read-only port. For more information on RAM mode in LatticeXP devices, please see details of additional technical documentation at the end of this data sheet.

Table 2-3. Number of Slices Required for Implementing Distributed RAM

	SPR16x2	**DPR16x2**
Number of Slices	1	2

Note: SPR = Single Port RAM, DPR = Dual Port RAM

Figure 2-4. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Figure 2-18. Group of Seven PIOs

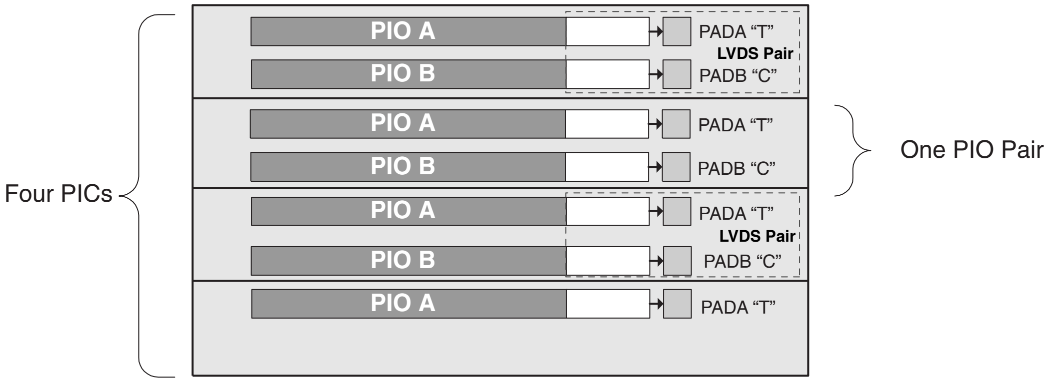
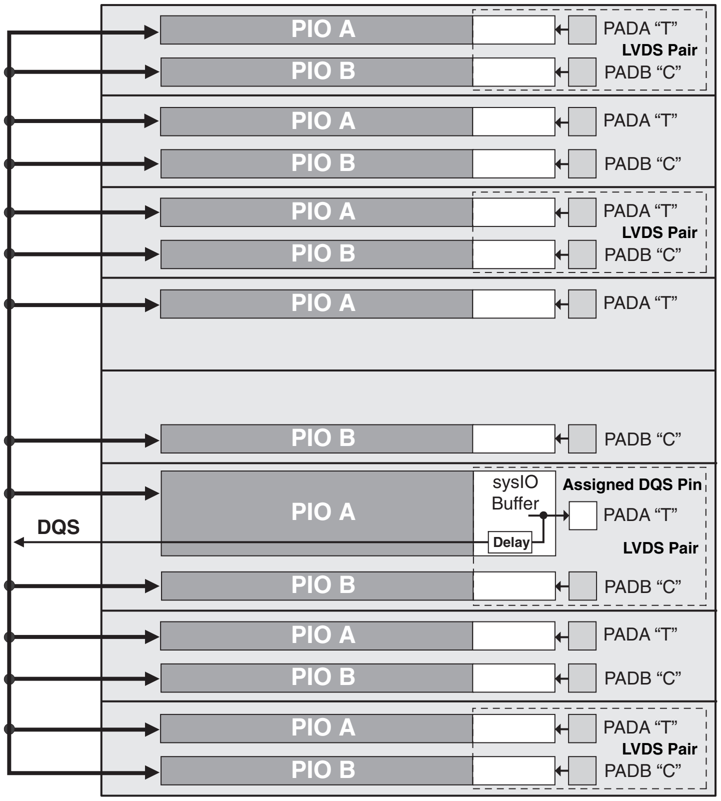


Figure 2-19. DQS Routing



PIO

The PIO contains four blocks: an input register block, output register block, tristate register block and a control logic block. These blocks contain registers for both single data rate (SDR) and double data rate (DDR) operation along with the necessary clock and selection logic. Programmable delay lines used to shift incoming clock and data signals are also included in these blocks.

Input Register Block

The input register block contains delay elements and registers that can be used to condition signals before they are passed to the device core. Figure 2-20 shows the diagram of the input register block.

Input signals are fed from the sysIO buffer to the input register block (as signal DI). If desired the input signal can bypass the register and delay elements and be used directly as a combinatorial signal (INDD), a clock (INCK) and

Figure 2-26. DQS Local Bus

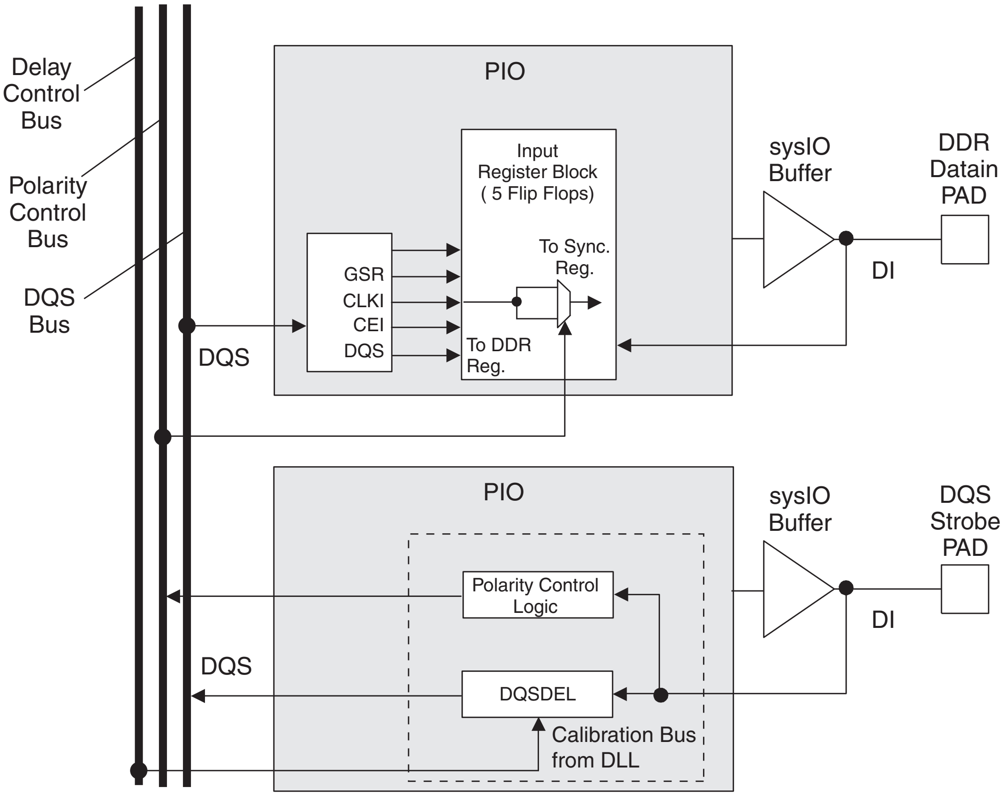


Figure 2-27. DLL Calibration Bus and DQS/DQS Transition Distribution

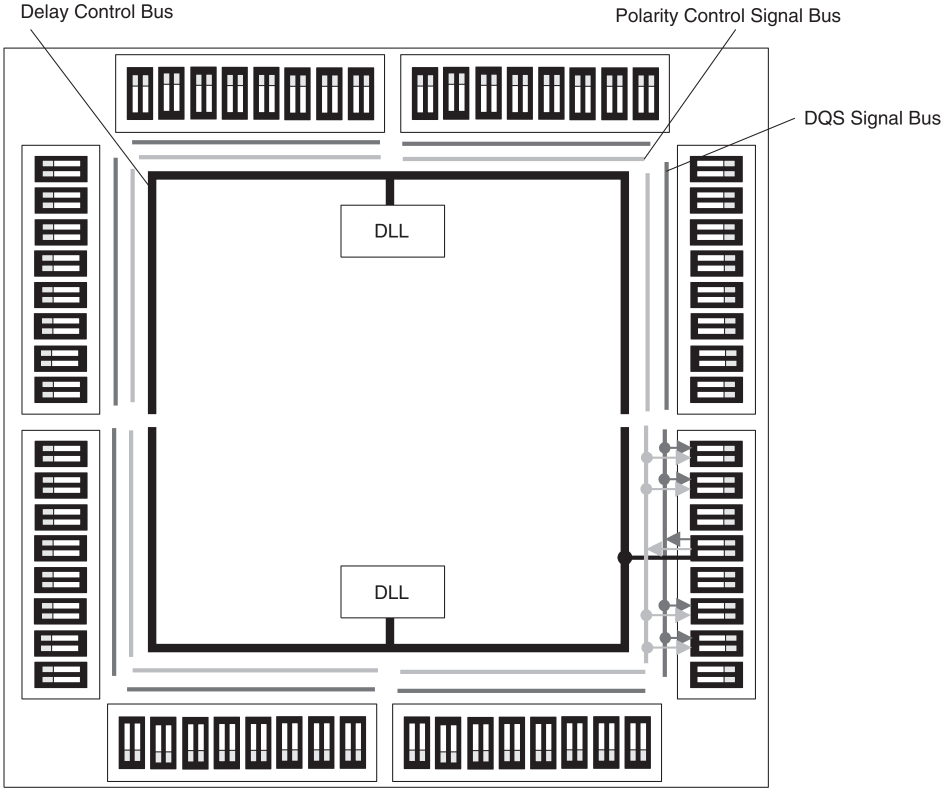


Figure 2-29 provides a pictorial representation of the different programming ports and modes available in the LatticeXP devices.

On power-up, the FPGA SRAM is ready to be configured with the sysCONFIG port active. The IEEE 1149.1 serial mode can be activated any time after power-up by sending the appropriate command through the TAP port.

Leave Alone I/O

When using 1532 mode for non-volatile memory programming, users may specify I/Os as high, low, tristated or held at current value. This provides excellent flexibility for implementing systems where reprogramming occurs on-the-fly.

TransFR (Transparent Field Reconfiguration)

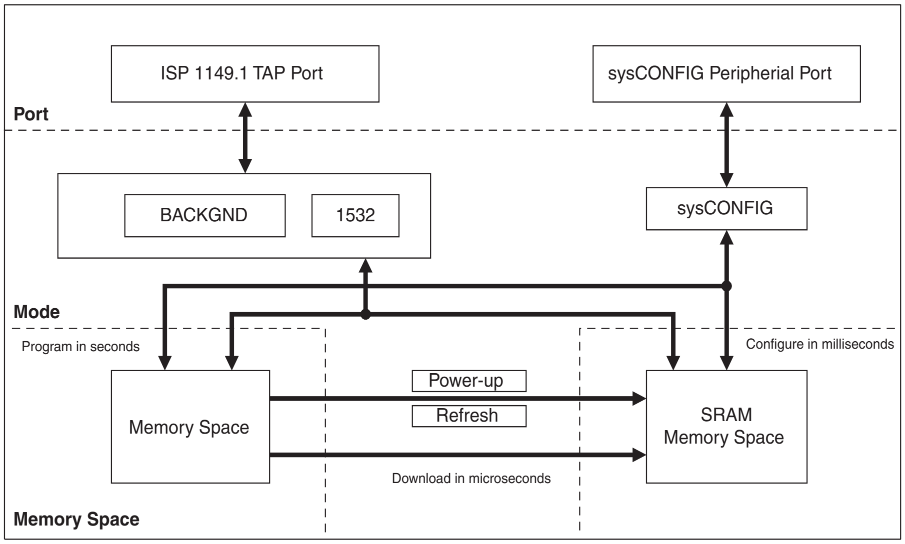
TransFR (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM command. See Lattice technical note #TN1087, *Minimizing System Interruption During Configuration Using TransFR Technology,* for details.

Security

The LatticeXP devices contain security bits that, when set, prevent the readback of the SRAM configuration and non-volatile memory spaces. Once set, the only way to clear security bits is to erase the memory space.

For more information on device configuration, please see details of additional technical documentation at the end of this data sheet.

Figure 2-29. ispXP Block Diagram



Internal Logic Analyzer Capability (ispTRACY)

All LatticeXP devices support an internal logic analyzer diagnostic feature. The diagnostic features provide capabilities similar to an external logic analyzer, such as programmable event and trigger condition and deep trace memory. This feature is enabled by Lattice's ispTRACY. The ispTRACY utility is added into the user design at compile time.

For more information on ispTRACY, please see information regarding additional technical documentation at the end of this data sheet.

Oscillator

Every LatticeXP device has an internal CMOS oscillator which is used to derive a master serial clock for configuration. The oscillator and the master serial clock run continuously in the configuration mode. The default value of the

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH}[1, 2, 4]	Input or I/O Leakage	$0 \leq V_{IN} \leq (V_{CCIO} - 0.2V)$	—	—	10	µA
		$(V_{CCIO} - 0.2V) < V_{IN} \leq 3.6V$	—	—	40	µA
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{IN} \leq 0.7 V_{CCIO}$	-30	—	-150	µA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) $\leq V_{IN} \leq V_{IH}$ (MAX)	30	—	150	µA
I_{BHLS}	Bus Hold Low sustaining current	$V_{IN} = V_{IL}$ (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High sustaining current	$V_{IN} = 0.7V_{CCIO}$	-30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive current	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	—	—	150	µA
I_{BHHO}	Bus Hold High Overdrive current	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	—	—	-150	µA
V_{BHT}	Bus Hold trip Points	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	V_{IL} (MAX)	—	V_{IH} (MIN)	V
C1	I/O Capacitance[3]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf
C2	Dedicated Input Capacitance[3]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. Not applicable to SLEEPN/TOE pin.
3. T_A 25°C, f = 1.0MHz
4. When V_{IH} is higher than V_{CCIO}, a transient current typically of 30ns in duration or less with a peak current of 6mA can be expected on the high-to-low transition.

Supply Current (Sleep Mode)[1, 2, 3]

Symbol	Parameter	Device	Typ.[4]	Max	Units
I_{CC}	Core Power Supply	LFXP3C	12	65	µA
		LFXP6C	14	75	µA
		LFXP10C	16	85	µA
		LFXP15C	18	95	µA
		LFXP20C	20	105	µA
I_{CCP}	PLL Power Supply (per PLL)	All LFXP ‘C’ Devices	1	5	µA
I_{CCAUX}	Auxiliary Power Supply	LFXP3C	2	90	µA
		LFXP6C	2	100	µA
		LFXP10C	2	110	µA
		LFXP15C	3	120	µA
		LFXP20C	4	130	µA
I_{CCIO}	Bank Power Supply[5]	LFXP3C	2	20	µA
		LFXP6C	2	22	µA
		LFXP10C	2	24	µA
		LFXP15C	3	27	µA
		LFXP20C	4	30	µA
I_{CCJ}	VCCJ Power Supply	All LFXP ‘C’ Devices	1	5	µA

1. Assumes all inputs are configured as LVCMOS and held at the VCCIO or GND.
2. Frequency 0MHz.
3. User pattern: blank.
4. T_A=25°C, power supplies at nominal voltage.
5. Per bank.

sysIO Recommended Operating Conditions

Standard	V_{CCIO}			V_{REF} (V)		
	Min.	**Typ.**	**Max.**	**Min.**	**Typ.**	**Max.**
LVCMOS 3.3	3.135	3.3	3.465	—	—	—
LVCMOS 2.5	2.375	2.5	2.625	—	—	—
LVCMOS 1.8	1.71	1.8	1.89	—	—	—
LVCMOS 1.5	1.425	1.5	1.575	—	—	—
LVCMOS 1.2	1.14	1.2	1.26	—	—	—
LVTTL	3.135	3.3	3.465	—	—	—
PCI33	3.135	3.3	3.465	—	—	—
SSTL18 Class I	1.71	1.8	1.89	0.833	0.9	0.969
SSTL2 Class I, II	2.375	2.5	2.625	1.15	1.25	1.35
SSTL3 Class I, II	3.135	3.3	3.465	1.3	1.5	1.7
HSTL15 Class I	1.425	1.5	1.575	0.68	0.75	0.9
HSTL15 Class III	1.425	1.5	1.575	—	0.9	—
HSTL 18 Class I, II	1.71	1.8	1.89	—	0.9	—
HSTL 18 Class III	1.71	1.8	1.89	—	1.08	—
LVDS	2.375	2.5	2.625	—	—	—
LVPECL[1]	3.135	3.3	3.465	—	—	—
BLVDS[1]	2.375	2.5	2.625	—	—	—

1. Inputs on chip. Outputs are implemented with the addition of external resistors.

sysIO Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input Voltage		0	—	2.4	V
V_{THD}	Differential Input Threshold		+/-100	—	—	mV
V_{CM}	Input Common Mode Voltage	100mV ≤ V_{THD}	$V_{THD}/2$	1.2	1.8	V
		200mV ≤ V_{THD}	$V_{THD}/2$	1.2	1.9	V
		350mV ≤ V_{THD}	$V_{THD}/2$	1.2	2.0	V
I_{IN}	Input current	Power on or power off	—	—	+/-10	µA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	R_T = 100 ohms	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	R_T = 100 ohms	0.9V	1.03	—	V
V_{OD}	Output voltage differential	(V_{OP} - V_{OM}), R_T = 100 ohms	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	(V_{OP} - V_{OM})/2, R_T = 100 ohms	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	V_{OD} = 0V Driver outputs shorted	—	—	6	mA

LatticeXP External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
General I/O Pin Parameters (Using Primary Clock without PLL)[1]									
t_{CO}	Clock to Output - PIO Output Register	LFXP3	—	5.12	—	6.12	—	7.43	ns
		LFXP6	—	5.30	—	6.34	—	7.69	ns
		LFXP10	—	5.52	—	6.60	—	8.00	ns
		LFXP15	—	5.72	—	6.84	—	8.29	ns
		LFXP20	—	5.97	—	7.14	—	8.65	ns
t_{SU}	Clock to Data Setup - PIO Input Register	LFXP3	-0.40	—	-0.28	—	-0.16	—	ns
		LFXP6	-0.33	—	-0.32	—	-0.30	—	ns
		LFXP10	-0.61	—	-0.71	—	-0.81	—	ns
		LFXP15	-0.71	—	-0.77	—	-0.87	—	ns
		LFXP20	-0.95	—	-1.14	—	-1.35	—	ns
t_H	Clock to Data Hold - PIO Input Register	LFXP3	2.10	—	2.50	—	2.98	—	ns
		LFXP6	2.28	—	2.72	—	3.24	—	ns
		LFXP10	3.02	—	3.51	—	3.71	—	ns
		LFXP15	2.70	—	3.22	—	3.85	—	ns
		LFXP20	2.95	—	3.52	—	4.21	—	ns
t_{SU_DEL}	Clock to Data Setup - PIO Input Register with Input Data Delay	LFXP3	2.38	—	2.49	—	2.66	—	ns
		LFXP6	2.92	—	3.18	—	3.42	—	ns
		LFXP10	2.72	—	2.75	—	2.84	—	ns
		LFXP15	2.99	—	3.13	—	3.18	—	ns
		LFXP20	4.47	—	4.56	—	4.80	—	ns
t_{H_DEL}	Clock to Data Hold - PIO Input Register with Input Data Delay	LFXP3	-0.70	—	-0.80	—	-0.92	—	ns
		LFXP6	-0.47	—	-0.38	—	-0.31	—	ns
		LFXP10	-0.60	—	-0.47	—	-0.32	—	ns
		LFXP15	-1.05	—	-0.98	—	-1.01	—	ns
		LFXP20	-0.80	—	-0.58	—	-0.31	—	ns
f_{MAX_IO}	Clock Frequency of I/O and PFU Register	All	—	400	—	360	—	320	MHz
DDR I/O Pin Parameters[2]									
t_{DVADQ}	Data Valid After DQS (DDR Read)	All	—	0.19	—	0.19	—	0.19	UI
t_{DVEDQ}	Data Hold After DQS (DDR Read)	All	0.67	—	0.67	—	0.67	—	UI
t_{DQVBS}	Data Valid Before DQS	All	0.20	—	0.20	—	0.20	—	UI
t_{DQVAS}	Data Valid After DQS	All	0.20	—	0.20	—	0.20	—	UI
f_{MAX_DDR}	DDR Clock Frequency	All	95	166	95	133	95	100	MHz
Primary and Secondary Clocks									
f_{MAX_PRI}	Frequency for Primary Clock Tree	All	—	450	—	412	—	375	MHz
t_{W_PRI}	Clock Pulse Width for Primary Clock	All	1.19	—	1.19	—	1.19	—	ns
t_{SKEW_PRI}	Primary Clock Skew within an I/O Bank	LFXP3/6/10/15	—	250	—	300	—	350	ps
		LFXP20	—	300	—	350	—	400	ps

1. General timing numbers based on LVCMOS 2.5, 12mA.
2. DDR timing numbers based on SSTL I/O.

Timing v.F0.11

LatticeXP Internal Timing Parameters[1] (Continued)

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.61	—	1.94	—	2.32	ns
PLL Parameters								
t_{RSTREC}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t_{RSTSU}	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.

Timing v.F0.11

LatticeXP Family Data Sheet
Pinout Information

November 2007 **Data Sheet DS1001**

Signal Descriptions

Signal Name	I/O	Descriptions
General Purpose		
P[Edge] [Row/Column Number*]_[A/B]	I/O	[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top). [Row/Column Number] indicates the PFU row or the column of the device on which the PIC exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number. [A/B] indicates the PIO within the PIC to which the pad is connected. Some of these user programmable pins are shared with special function pins. These pin when not used as special purpose pins can be programmed as I/Os for user logic. During configuration, the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.
GSRN	I	Global RESET signal. (Active low). Any I/O pin can be configured to be GSRN.
NC	—	No connect.
GND	—	GND - Ground. Dedicated Pins.
V_{CC}	—	VCC - The power supply pins for core logic. Dedicated Pins.
V_{CCAUX}	—	V_{CCAUX} - The Auxiliary power supply pin. It powers all the differential and referenced input buffers. Dedicated Pins.
V_{CCP0}	—	Voltage supply pins for ULM0PLL (and LLM1PLL[1]).
V_{CCP1}	—	Voltage supply pins for URM0PLL (and LRM1PLL[1]).
GNDP0	—	Ground pins for ULM0PLL (and LLM1PLL[1]).
GNDP1	—	Ground pins for URM0PLL (and LRM1PLL[1]).
V_{CCIOx}	—	V_{CCIO} - The power supply pins for I/O bank x. Dedicated Pins.
$V_{REF1(x)}$, $V_{REF2(x)}$	—	Reference supply pins for I/O bank x. Pre-determined pins in each bank are assigned as V_{REF} inputs. When not used, they may be used as I/O pins.
PLL and Clock Functions (Used as user programmable I/O pins when not in use for PLL or clock pins)		
[LOC][num]_PLL[T, C]_IN_A	—	Reference clock (PLL) input Pads: ULM, LLM, URM, LRM, num = row from center, T = true and C = complement, index A, B, C...at each side.
[LOC][num]_PLL[T, C]_FB_A	—	Optional feedback (PLL) input Pads: ULM, LLM, URM, LRM, num = row from center, T = true and C = complement, index A, B, C...at each side.
PCLK[T, C]_[n:0]_[3:0]	—	Primary Clock Pads, T = true and C = complement, n per side, indexed by bank and 0,1, 2, 3 within bank.
[LOC]DQS[num]	—	DQS input Pads: T (Top), R (Right), B (Bottom), L (Left), DQS, num = Ball function number. Any pad can be configured to be DQS output.

Signal Descriptions (Cont.)

Signal Name	I/O	Descriptions
Test and Programming (Dedicated pins. Pull-up is enabled on input pins during configuration.)		
TMS	I	Test Mode Select input, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data in pin, used to load data into device using 1149.1 state machine. After power-up, this TAP port can be activated for configuration by sending appropriate command. (Note: once a configuration port is selected it is locked. Another configuration port cannot be selected until the power-up sequence).
TDO	O	Output pin -Test Data out pin used to shift data out of device using 1149.1.
V_{CCJ}	—	V_{CCJ} - The power supply pin for JTAG Test Access Port.
Configuration Pads (used during sysCONFIG)		
CFG[1:0]	I	Mode pins used to specify configuration modes values latched on rising edge of INITN. During configuration, a pull-up is enabled.
INITN	I/O	Open Drain pin - Indicates the FPGA is ready to be configured. During configuration, a pull-up is enabled. If CFG1 and CFG0 are high (SDM) then this pin is pulled low.
PROGRAMN	I	Initiates configuration sequence when asserted low. This pin always has an active pull-up.
DONE	I/O	Open Drain pin - Indicates that the configuration sequence is complete, and the startup sequence is in progress.
CCLK	I/O	Configuration Clock for configuring an FPGA in sysCONFIG mode.
BUSY	I/O	Generally not used. After configuration it is a user-programmable I/O pin.
CSN	I	sysCONFIG chip select (Active low). During configuration, a pull-up is enabled. After configuration it is user a programmable I/O pin.
CS1N	I	sysCONFIG chip select (Active Low). During configuration, a pull-up is enabled. After configuration it is user programmable I/O pin
WRITEN	I	Write Data on Parallel port (Active low). After configuration it is a user programmable I/O pin
D[7:0]	I/O	sysCONFIG Port Data I/O. After configuration these are user programmable I/O pins.
DOUT, CSON	O	Output for serial configuration data (rising edge of CCLK) when using sysCONFIG port. After configuration, it is a user-programmable I/O pin.
DI	I	Input for serial configuration data (clocked with CCLK) when using sysCONFIG port. During configuration, a pull-up is enabled. After configuration it is a user-programmable I/O pin.
SLEEPN[2]	I	Sleep Mode pin - Active low sleep pin.þ When this pin is held high, the device operates normally.þ When driven low, the device moves into Sleep Mode after a specified time.This pin has a weak internal pull-up, but when not used an external pull-up to V_{CC} is recommended.
TOE[3]	I	Test Output Enable tri-states all I/O pins when driven low. This pin has a weak internal pull-up, but when not used an external pull-up to V_{CC} is recommended.

1. Applies toþ LFXP10, LFXP15 and LFXP20 only.
2. Applies to LFXP “C” devices only.
3. Applies to LFXP “E” devices only.

LFXP3 & LFXP6 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	**Bank**	**Differential**	**Dual Function**	**Pin Function**	**Bank**	**Differential**	**Dual Function**
139	PR7A	2	T[3]	DQS	PR7A	2	T[3]	DQS
140	VCCIO2	2	-	-	VCCIO2	2	-	-
141	PR6B	2	-	VREF1_2	PR6B	2	-	VREF1_2
142	PR5A	2	-	VREF2_2	PR5A	2	-	VREF2_2
143	GNDIO2	2	-	-	GNDIO2	2	-	-
144	PR4B	2	C[3]	-	PR4B	2	C[3]	-
145	PR4A	2	T[3]	-	PR4A	2	T[3]	-
146	PR3B	2	C	RUM0_PLLC_FB_A	PR3B	2	C	RUM0_PLLC_FB_A
147	PR3A	2	T	RUM0_PLLT_FB_A	PR3A	2	T	RUM0_PLLT_FB_A
148	PR2B	2	C[3]	-	PR2B	2	C[3]	-
149	VCCIO2	2	-	-	VCCIO2	2	-	-
150	PR2A	2	T[3]	-	PR2A	2	T[3]	-
151	VCC	-	-	-	VCC	-	-	-
152	VCCAUX	-	-	-	VCCAUX	-	-	-
153	TDO	-	-	-	TDO	-	-	-
154	VCCJ	-	-	-	VCCJ	-	-	-
155	TDI	-	-	-	TDI	-	-	-
156	TMS	-	-	-	TMS	-	-	-
157	TCK	-	-	-	TCK	-	-	-
158	VCC	-	-	-	VCC	-	-	-
159	PT25A	1	-	VREF1_1	PT28A	1	-	VREF1_1
160	PT24B	1	C	-	PT27B	1	C	-
161	PT24A	1	T	-	PT27A	1	T	-
162	PT23A	1	-	D0	PT26A	1	-	D0
163	GNDIO1	1	-	-	GNDIO1	1	-	-
164	PT22B	1	C	D1	PT25B	1	C	D1
165	PT22A	1	T	VREF2_1	PT25A	1	T	VREF2_1
166	PT21A	1	-	D2	PT24A	1	-	D2
167	VCCIO1	1	-	-	VCCIO1	1	-	-
168	PT20B	1	C	D3	PT23B	1	C	D3
169	PT20A	1	T	-	PT23A	1	T	-
170	PT19B	1	C	-	PT22B	1	C	-
171	PT19A	1	T	DQS	PT22A	1	T	DQS
172	GNDIO1	1	-	-	GNDIO1	1	-	-
173	PT18B	1	-	-	PT21B	1	-	-
174	PT17A	1	-	D4	PT20A	1	-	D4
175	PT16B	1	C	-	PT19B	1	C	-
176	PT16A	1	T	D5	PT19A	1	T	D5
177	VCCIO1	1	-	-	VCCIO1	1	-	-
178	PT15B	1	C	D6	PT18B	1	C	D6
179	PT15A	1	T	-	PT18A	1	T	-
180	PT14B	1	-	D7	PT17B	1	-	D7
181	GND	-	-	-	GND	-	-	-
182	VCC	-	-	-	VCC	-	-	-
183	PT13B	0	C	BUSY	PT16B	0	C	BUSY
184	GNDIO0	0	-	-	GNDIO0	0	-	-

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP6				LFXP10			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
R8	PB16A	5	T	-	PB20A	5	T	-
T9	PB16B	5	C	-	PB20B	5	C	-
R9	PB17A	4	T	-	PB21A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
P9	PB17B	4	C	-	PB21B	4	C	-
T10	PB18A	4	T	PCLKT4_0	PB22A	4	T	PCLKT4_0
T11	PB18B	4	C	PCLKC4_0	PB22B	4	C	PCLKC4_0
R10	PB19A	4	T	-	PB23A	4	T	-
P10	PB19B	4	C	-	PB23B	4	C	-
N9	PB20A	4	-	-	PB24A	4	-	-
M9	PB21B	4	-	-	PB25B	4	-	-
R12	PB22A	4	T	DQS	PB26A	4	T	DQS
-	GNDIO4	4	-	-	GNDIO4	4	-	-
T12	PB22B	4	C	VREF1_4	PB26B	4	C	VREF1_4
P13	PB23A	4	T	-	PB27A	4	T	-
R13	PB23B	4	C	-	PB27B	4	C	-
M11	PB24A	4	T	-	PB28A	4	T	-
N11	PB24B	4	C	-	PB28B	4	C	-
N10	PB25A	4	T	-	PB29A	4	T	-
M10	PB25B	4	C	-	PB29B	4	C	-
T13	PB26A	4	T	-	PB30A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
P14	PB26B	4	C	-	PB30B	4	C	-
R11	PB27A	4	T	VREF2_4	PB31A	4	T	VREF2_4
P12	PB27B	4	C	-	PB31B	4	C	-
T14	PB28A	4	-	-	PB32A	4	-	-
R14	PB29B	4	-	-	PB33B	4	-	-
P11	PB30A	4	T	DQS	PB34A	4	T	DQS
N12	PB30B	4	C	-	PB34B	4	C	-
T15	PB31A	4	T	-	PB35A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
R15	PB31B	4	C	-	PB35B	4	C	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
P15	PR26B	3	C[3]	-	PR34B	3	C	RLM0_PLLC_FB_A
N15	PR26A	3	T[3]	-	PR34A	3	T	RLM0_PLLT_FB_A
P16	PR24B	3	C[3]	-	PR33B	3	C[3]	-
R16	PR24A	3	T[3]	DQS	PR33A	3	T[3]	DQS
M15	PR15B	3	-	-	PR32B	3	-	-
N14	PR23B	3	-	VREF1_3	PR31A	3	-	VREF1_3
-	GNDIO3	3	-	-	GNDIO3	3	-	-
M14	PR25B	3	C	-	PR29B	3	C	-
L13	PR25A	3	T	-	PR29A	3	T	-

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
A9	PT27A	1	T	-	PT31A	1	T	-
C9	PT26B	1	C	D7	PT30B	1	C	D7
C8	PT26A	1	T	-	PT30A	1	T	-
E9	PT25B	0	C	BUSY	PT29B	0	C	BUSY
-	GNDIO0	0	-	-	GNDIO0	0	-	-
B8	PT25A	0	T	CS1N	PT29A	0	T	CS1N
A8	PT24B	0	C	PCLKC0_0	PT28B	0	C	PCLKC0_0
A7	PT24A	0	T	PCLKT0_0	PT28A	0	T	PCLKT0_0
B7	PT23B	0	C	-	PT27B	0	C	-
C7	PT23A	0	T	DQS	PT27A	0	T	DQS
E8	PT22B	0	-	-	PT26B	0	-	-
D8	PT21A	0	-	DOUT	PT25A	0	-	DOUT
A6	PT20B	0	C	-	PT24B	0	C	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
C6	PT20A	0	T	WRITEN	PT24A	0	T	WRITEN
E7	PT19B	0	C	-	PT23B	0	C	-
D7	PT19A	0	T	VREF1_0	PT23A	0	T	VREF1_0
A5	PT18B	0	C	-	PT22B	0	C	-
B5	PT18A	0	T	DI	PT22A	0	T	DI
A4	PT17B	0	C	-	PT21B	0	C	-
B6	PT17A	0	T	CSN	PT21A	0	T	CSN
E6	PT16B	0	C	-	PT20B	0	C	-
D6	PT16A	0	T	-	PT20A	0	T	-
D5	PT15B	0	C	VREF2_0	PT19B	0	C	VREF2_0
A3	PT15A	0	T	DQS	PT19A	0	T	DQS
B3	PT14B	0	-	-	PT18B	0	-	-
B2	PT13A	0	-	-	PT17A	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
A2	PT12B	0	C	-	PT16B	0	C	-
B1	PT12A	0	T	-	PT16A	0	T	-
F5	PT11B	0	C	-	PT15B	0	C	-
C5	PT11A	0	T	-	PT15A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
C4	CFG0	0	-	-	CFG0	0	-	-
B4	CFG1	0	-	-	CFG1	0	-	-
C3	DONE	0	-	-	DONE	0	-	-
A1	GND	-	-	-	GND	-	-	-
A16	GND	-	-	-	GND	-	-	-
F11	GND	-	-	-	GND	-	-	-
F6	GND	-	-	-	GND	-	-	-

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

	LFXP10				LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
U1	PL25A	6	T	LLM0_PLLT_IN_A	PL29A	6	T	LLM0_PLLT_IN_A	PL33A	6	T	LLM0_PLLT_IN_A
T2	PL25B	6	C	LLM0_PLLC_IN_A	PL29B	6	C	LLM0_PLLC_IN_A	PL33B	6	C	LLM0_PLLC_IN_A
V1	PL26A	6	T[3]	-	PL30A	6	T[3]	-	PL34A	6	T[3]	-
U2	PL26B	6	C[3]	-	PL30B	6	C[3]	-	PL34B	6	C[3]	-
W1	PL28A	6	T[3]	-	PL32A	6	T[3]	-	PL36A	6	T[3]	-
V2	PL28B	6	C[3]	-	PL32B	6	C[3]	-	PL36B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	-	-	-	GNDIO6	6	-	-
P3	PL29A	6	T	-	PL33A	6	T	-	PL37A	6	T	-
P4	PL29B	6	C	-	PL33B	6	C	-	PL37B	6	C	-
Y1	PL30A	6	T[3]	-	PL34A	6	T[3]	-	PL38A	6	T[3]	-
W2	PL30B	6	C[3]	-	PL34B	6	C[3]	-	PL38B	6	C[3]	-
R3	PL31A	6	-	VREF2_6	PL35A	6	-	VREF2_6	PL39A	6	-	VREF2_6
R4	PL32B	6	-	-	PL36B	6	-	-	PL40B	6	-	-
T3	PL33A	6	T[3]	DQS	PL37A	6	T[3]	DQS	PL41A	6	T[3]	DQS
T4	PL33B	6	C[3]	-	PL37B	6	C[3]	-	PL41B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-	GNDIO6	6	-	-
V4	PL34A	6	T	LLM0_PLLT_FB_A	PL38A	6	T	LLM0_PLLT_FB_A	PL42A	6	T	LLM0_PLLT_FB_A
V3	PL34B	6	C	LLM0_PLLC_FB_A	PL38B	6	C	LLM0_PLLC_FB_A	PL42B	6	C	LLM0_PLLC_FB_A
U4	PL35A	6	T[3]	-	PL39A	6	T[3]	-	PL43A	6	T[3]	-
U3	PL35B	6	C[3]	-	PL39B	6	C[3]	-	PL43B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-	GNDIO6	6	-	-
W5	SLEEPN[1]/ TOE[2]	-	-	-	SLEEPN[1]/ TOE[2]	-	-	-	SLEEPN[1]/ TOE[2]	-	-	-
Y2	INITN	5	-	-	INITN	5	-	-	INITN	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-	GNDIO5	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-	GNDIO5	5	-	-
Y3	-	-	-	-	PB3B	5	-	-	PB7B	5	-	-
W3	-	-	-	-	PB4A	5	T	-	PB8A	5	T	-
W4	-	-	-	-	PB4B	5	C	-	PB8B	5	C	-
AA2	-	-	-	-	PB5A	5	-	-	PB9A	5	-	-
AA1	-	-	-	-	PB6B	5	-	-	PB10B	5	-	-
W6	PB2A	5	-	-	PB7A	5	T	DQS	PB11A	5	T	DQS
W7	-	-	-	-	PB7B	5	C	-	PB11B	5	C	-
Y4	PB3A	5	T	-	PB8A	5	T	-	PB12A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-	GNDIO5	5	-	-
Y5	PB3B	5	C	-	PB8B	5	C	-	PB12B	5	C	-
AB2	PB4A	5	T	-	PB9A	5	T	-	PB13A	5	T	-
AA3	PB4B	5	C	-	PB9B	5	C	-	PB13B	5	C	-
AB3	PB5A	5	T	-	PB10A	5	T	-	PB14A	5	T	-
AA4	PB5B	5	C	-	PB10B	5	C	-	PB14B	5	C	-
W8	PB6A	5	T	-	PB11A	5	T	-	PB15A	5	T	-
W9	PB6B	5	C	-	PB11B	5	C	-	PB15B	5	C	-
AB4	PB7A	5	T	VREF1_5	PB12A	5	T	VREF1_5	PB16A	5	T	VREF1_5
-	GNDIO5	5	-	-	GNDIO5	5	-	-	GNDIO5	5	-	-
AA5	PB7B	5	C	-	PB12B	5	C	-	PB16B	5	C	-
AB5	PB8A	5	-	-	PB13A	5	-	-	PB17A	5	-	-
Y6	PB9B	5	-	-	PB14B	5	-	-	PB18B	5	-	-
AA6	PB10A	5	T	DQS	PB15A	5	T	DQS	PB19A	5	T	DQS
AB6	PB10B	5	C	-	PB15B	5	C	-	PB19B	5	C	-
Y9	PB11A	5	T	-	PB16A	5	T	-	PB20A	5	T	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
AB5	PB16A	5	T	-	PB20A	5	T	-
AB6	PB16B	5	C	-	PB20B	5	C	-
AA8	PB17A	5	T	-	PB21A	5	T	-
AA9	PB17B	5	C	VREF2_5	PB21B	5	C	VREF2_5
W10	PB18A	5	T	-	PB22A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
V10	PB18B	5	C	-	PB22B	5	C	-
AB7	PB19A	5	T	-	PB23A	5	T	-
AB8	PB19B	5	C	-	PB23B	5	C	-
AB9	PB20A	5	T	-	PB24A	5	T	-
AB10	PB20B	5	C	-	PB24B	5	C	-
Y10	PB21A	5	-	-	PB25A	5	-	-
AA10	PB22B	5	-	-	PB26B	5	-	-
W11	PB23A	5	T	DQS	PB27A	5	T	DQS
V11	PB23B	5	C	-	PB27B	5	C	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
Y11	PB24A	5	T	-	PB28A	5	T	-
AA11	PB24B	5	C	-	PB28B	5	C	-
AB11	PB25A	5	T	-	PB29A	5	T	-
AB12	PB25B	5	C	-	PB29B	5	C	-
Y12	PB26A	4	T	-	PB30A	4	T	-
AA12	PB26B	4	C	-	PB30B	4	C	-
W12	PB27A	4	T	PCLKT4_0	PB31A	4	T	PCLKT4_0
V12	PB27B	4	C	PCLKC4_0	PB31B	4	C	PCLKC4_0
-	GNDIO4	4	-	-	GNDIO4	4	-	-
AB13	PB28A	4	T	-	PB32A	4	T	-
AB14	PB28B	4	C	-	PB32B	4	C	-
AA13	PB29A	4	-	-	PB33A	4	-	-
Y13	PB30B	4	-	-	PB34B	4	-	-
AB15	PB31A	4	T	DQS	PB35A	4	T	DQS
AB16	PB31B	4	C	VREF1_4	PB35B	4	C	VREF1_4
V13	PB32A	4	T	-	PB36A	4	T	-
W13	PB32B	4	C	-	PB36B	4	C	-
AA14	PB33A	4	T	-	PB37A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
AA15	PB33B	4	C	-	PB37B	4	C	-
AB17	PB34A	4	T	-	PB38A	4	T	-
AB18	PB34B	4	C	-	PB38B	4	C	-
W14	PB35A	4	T	-	PB39A	4	T	-
Y14	PB35B	4	C	-	PB39B	4	C	-
U14	PB36A	4	T	VREF2_4	PB40A	4	T	VREF2_4
V14	PB36B	4	C	-	PB40B	4	C	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	**Ball Function**	**Bank**	**Differential**	**Dual Function**	**Ball Function**	**Bank**	**Differential**	**Dual Function**
R18	PR38B	3	C	RLM0_PLLC_FB_A	PR42B	3	C	RLM0_PLLC_FB_A
R17	PR38A	3	T	RLM0_PLLT_FB_A	PR42A	3	T	RLM0_PLLT_FB_A
Y22	PR37B	3	C[3]	-	PR41B	3	C[3]	-
Y21	PR37A	3	T[3]	DQS	PR41A	3	T[3]	DQS
W22	PR36B	3	-	-	PR40B	3	-	-
W21	PR35A	3	-	VREF1_3	PR39A	3	-	VREF1_3
P17	PR34B	3	C[3]	-	PR38B	3	C[3]	-
P18	PR34A	3	T[3]	-	PR38A	3	T[3]	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
R19	PR33B	3	C	-	PR37B	3	C	-
R20	PR33A	3	T	-	PR37A	3	T	-
V22	PR32B	3	C[3]	-	PR36B	3	C[3]	-
V21	PR32A	3	T[3]	-	PR36A	3	T[3]	-
U22	PR30B	3	C[3]	-	PR34B	3	C[3]	-
U21	PR30A	3	T[3]	-	PR34A	3	T[3]	-
P19	PR29B	3	C	RLM0_PLLC_IN_A	PR33B	3	C	RLM0_PLLC_IN_A
P20	PR29A	3	T	RLM0_PLLT_IN_A	PR33A	3	T	RLM0_PLLT_IN_A
-	GNDIO3	3	-	-	GNDIO3	3	-	-
T22	PR28B	3	C[3]	-	PR32B	3	C[3]	-
T21	PR28A	3	T[3]	DQS	PR32A	3	T[3]	DQS
R22	PR27B	3	-	-	PR31B	3	-	-
R21	PR26A	3	-	VREF2_3	PR30A	3	-	VREF2_3
N19	PR25B	3	C[3]	-	PR29B	3	C[3]	-
N20	PR25A	3	T[3]	-	PR29A	3	T[3]	-
N18	PR24B	3	C	-	PR28B	3	C	-
M18	PR24A	3	T	-	PR28A	3	T	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
P22	PR23B	3	C[3]	-	PR27B	3	C[3]	-
P21	PR23A	3	T[3]	-	PR27A	3	T[3]	-
N22	-	-	-	-	PR26B	3	C[3]	-
N21	-	-	-	-	PR26A	3	T[3]	-
M19	-	-	-	-	PR25B	3	-	-
M20	GNDP1	-	-	-	GNDP1	-	-	-
L18	VCCP1	-	-	-	VCCP1	-	-	-
M21	-	-	-	-	PR24A	2	-	-
M22	PR22B	2	C[3]	-	PR23B	2	C[3]	-
L22	PR22A	2	T[3]	-	PR23A	2	T[3]	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
L19	-	-	-	-	PR22B	2	C[3]	-
L20	-	-	-	-	PR22A	2	T[3]	-
L21	PR21B	2	C	PCLKC2_0	PR21B	2	C	PCLKC2_0
K22	PR21A	2	T	PCLKT2_0	PR21A	2	T	PCLKT2_0

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1052 - Power Estimation and Management for LatticeECP/EC and LatticeXP Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

Conventional Packaging

Commercial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3C-3Q208C	136	1.8/2.5/3.3V	-3	PQFP	208	COM	3.1K
LFXP3C-4Q208C	136	1.8/2.5/3.3V	-4	PQFP	208	COM	3.1K
LFXP3C-5Q208C	136	1.8/2.5/3.3V	-5	PQFP	208	COM	3.1K
LFXP3C-3T144C	100	1.8/2.5/3.3V	-3	TQFP	144	COM	3.1K
LFXP3C-4T144C	100	1.8/2.5/3.3V	-4	TQFP	144	COM	3.1K
LFXP3C-5T144C	100	1.8/2.5/3.3V	-5	TQFP	144	COM	3.1K
LFXP3C-3T100C	62	1.8/2.5/3.3V	-3	TQFP	100	COM	3.1K
LFXP3C-4T100C	62	1.8/2.5/3.3V	-4	TQFP	100	COM	3.1K
LFXP3C-5T100C	62	1.8/2.5/3.3V	-5	TQFP	100	COM	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	5.8K
LFXP6C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	5.8K
LFXP6C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	5.8K
LFXP6C-3Q208C	142	1.8/2.5/3.3V	-3	PQFP	208	COM	5.8K
LFXP6C-4Q208C	142	1.8/2.5/3.3V	-4	PQFP	208	COM	5.8K
LFXP6C-5Q208C	142	1.8/2.5/3.3V	-5	PQFP	208	COM	5.8K
LFXP6C-3T144C	100	1.8/2.5/3.3V	-3	TQFP	144	COM	5.8K
LFXP6C-4T144C	100	1.8/2.5/3.3V	-4	TQFP	144	COM	5.8K
LFXP6C-5T144C	100	1.8/2.5/3.3V	-5	TQFP	144	COM	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10C-3F388C	244	1.8/2.5/3.3V	-3	fpBGA	388	COM	9.7K
LFXP10C-4F388C	244	1.8/2.5/3.3V	-4	fpBGA	388	COM	9.7K
LFXP10C-5F388C	244	1.8/2.5/3.3V	-5	fpBGA	388	COM	9.7K
LFXP10C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	9.7K
LFXP10C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	9.7K
LFXP10C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	9.7K

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20C-3FN484C	340	1.8/2.5/3.3V	-3	fpBGA	484	COM	19.7K
LFXP20C-4FN484C	340	1.8/2.5/3.3V	-4	fpBGA	484	COM	19.7K
LFXP20C-5FN484C	340	1.8/2.5/3.3V	-5	fpBGA	484	COM	19.7K
LFXP20C-3FN388C	268	1.8/2.5/3.3V	-3	fpBGA	388	COM	19.7K
LFXP20C-4FN388C	268	1.8/2.5/3.3V	-4	fpBGA	388	COM	19.7K
LFXP20C-5FN388C	268	1.8/2.5/3.3V	-5	fpBGA	388	COM	19.7K
LFXP20C-3FN256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	19.7K
LFXP20C-4FN256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	19.7K
LFXP20C-5FN256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	19.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3E-3QN208C	136	1.2V	-3	PQFP	208	COM	3.1K
LFXP3E-4QN208C	136	1.2V	-4	PQFP	208	COM	3.1K
LFXP3E-5QN208C	136	1.2V	-5	PQFP	208	COM	3.1K
LFXP3E-3TN144C	100	1.2V	-3	TQFP	144	COM	3.1K
LFXP3E-4TN144C	100	1.2V	-4	TQFP	144	COM	3.1K
LFXP3E-5TN144C	100	1.2V	-5	TQFP	144	COM	3.1K
LFXP3E-3TN100C	62	1.2V	-3	TQFP	100	COM	3.1K
LFXP3E-4TN100C	62	1.2V	-4	TQFP	100	COM	3.1K
LFXP3E-5TN100C	62	1.2V	-5	TQFP	100	COM	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6E-3FN256C	188	1.2V	-3	fpBGA	256	COM	5.8K
LFXP6E-4FN256C	188	1.2V	-4	fpBGA	256	COM	5.8K
LFXP6E-5FN256C	188	1.2V	-5	fpBGA	256	COM	5.8K
LFXP6E-3QN208C	142	1.2V	-3	PQFP	208	COM	5.8K
LFXP6E-4QN208C	142	1.2V	-4	PQFP	208	COM	5.8K
LFXP6E-5QN208C	142	1.2V	-5	PQFP	208	COM	5.8K
LFXP6E-3TN144C	100	1.2V	-3	TQFP	144	COM	5.8K
LFXP6E-4TN144C	100	1.2V	-4	TQFP	144	COM	5.8K
LFXP6E-5TN144C	100	1.2V	-5	TQFP	144	COM	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10E-3FN388C	244	1.2V	-3	fpBGA	388	COM	9.7K
LFXP10E-4FN388C	244	1.2V	-4	fpBGA	388	COM	9.7K
LFXP10E-5FN388C	244	1.2V	-5	fpBGA	388	COM	9.7K
LFXP10E-3FN256C	188	1.2V	-3	fpBGA	256	COM	9.7K
LFXP10E-4FN256C	188	1.2V	-4	fpBGA	256	COM	9.7K
LFXP10E-5FN256C	188	1.2V	-5	fpBGA	256	COM	9.7K